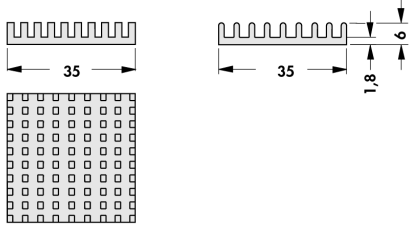
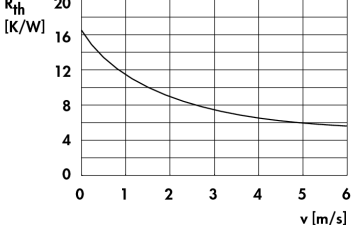
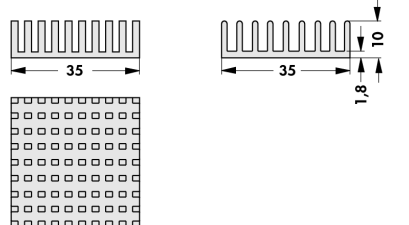
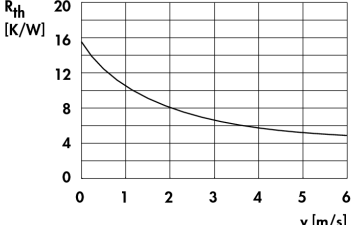
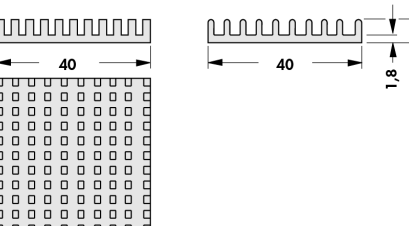
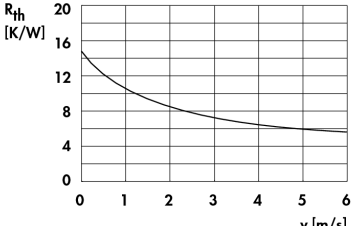
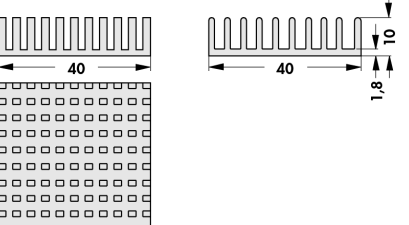
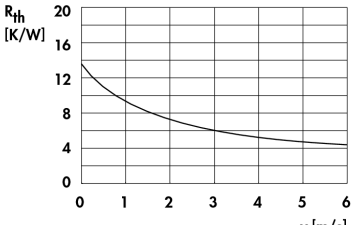
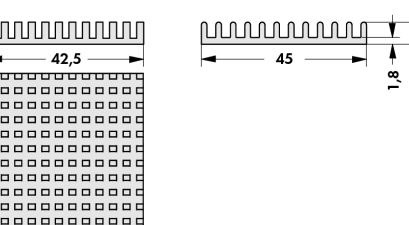
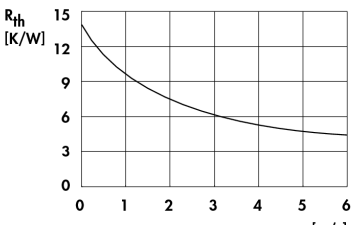


## Heatsinks for PGAs and BGAs

|   |   |   |
|---|---|---|
| <b>art. no.</b><br><br><b>ICK BGA 35 x 35</b><br>WLF ... 35 x 35      |    |    |
| <b>art. no.</b><br><br><b>ICK BGA 35 x 35 x 10</b><br>WLF ... 35 x 35 |    |    |
| <b>art. no.</b><br><br><b>ICK BGA 40 x 40</b><br>WLF ... 40 x 40      |    |    |
| <b>art. no.</b><br><br><b>ICK BGA 40 x 40 x 10</b><br>WLF ... 40 x 40 |   |   |
| <b>art. no.</b><br><br><b>ICK BGA 42,5 x 45</b><br>WLF ... 42,5 x 45  |  |  |

**B 15**

Thermal conduct. foil WLFT 404/405 → E 5  
 Thermal conductive glue → E 14  
 Thermal conductive paste → E 12  
 Processor overview → B 2 - 7

SMD-heatsinks → B 25 - 27  
 Mounting material for semiconduct. → E 34 - 38  
 Hole pattern → A 21  
 Technical introduction → A 2 - 7